

30V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)} max	I _D max $T_A = 25^{\circ}C$ (Notes 3)
-30V	45 m Ω @ V _{GS} = -10V	-7.5A
	70 m $Ω @ V_{GS} = -4.5V$	-5.9A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor control
- DC-DC Converters
- Power management functions
- · Relay and solenoid driving

Features and Benefits

- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- "Green" component. Lead Free Finish / RoHS compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability

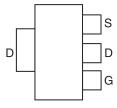
Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper lead frame.
 Solderable per MIL-STD-202, Method 208
- Weight: 0.112 grams (approximate)

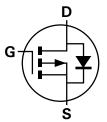
SOT223



Top View



Pin Out - Top View



Equivalent Circuit

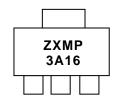
Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel	
ZXMP3A16GTA	ZXMP3A16	7	12	1,000	
ZXMP3A16GTC	ZXMP3A16	13	12	4,000	

Note: 1. Diodes, Inc. defines "Green" products as those which are RoHS compliant and contain no halogens or antimony compounds. All applicable RoHS

exemptions applied. Further information about Diodes Inc.'s "Green" Policy can be found on our website.

Marking Information



ZXMP = Product Type Marking Code, Line 1 3A16 = Product Type Marking Code, Line 2





Maximum Ratings @T_A = 25°C unless otherwise specified

	Characteristic		Symbol	Value	Unit	
Drain-Source voltage			V_{DSS}	-30	V	
Gate-Source voltage			V _{GS}	±20	V	
Continuous Drain current		(Note 3)		-7.5		
	$V_{GS} = 10V$	$T_A = 70$ °C (Note 3)	I _D	-6.0	Α	
		(Note 2)		-5.4		
Pulsed Drain current V _{GS} = 10V (Note		(Note 4)	I _{DM}	-24.9	Α	
Continuous Source current (Body diode) (Note 3)		(Note 3)	I _S	-3.2	Α	
Pulsed Source current (Body diode) (Note 4)		(Note 4)	I _{SM}	-24.9	Α	

Thermal Characteristics @TA = 25°C unless otherwise specified

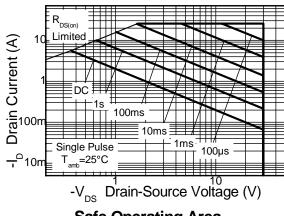
Characteristic	Symbol	Value	Unit		
Power dissipation	(Note 2)		2.0 16	W	
Linear derating factor	(Note 3)	P _D	3.9 31	mW/°C	
Thermal Pasistanes, Junation to Ambient	(Note 2)	D	62.5		
Thermal Resistance, Junction to Ambient	(Note 3)	$R_{ hetaJA}$	32.2	°C/W	
Thermal Resistance, Junction to Lead	(Note 5)	$R_{ heta JL}$	8.51		
Operating and storage temperature range		T _J , T _{STG}	-55 to 150	°C	

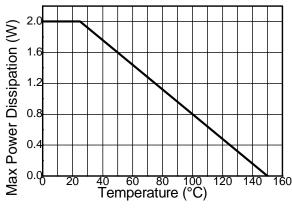
Notes:

- 2. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is 2. For a device strate modified of 25mm x 25mm x 1.5mm rA4 PCB with high coverage of single sided 102 copper, in still all conditions, the device is measured when operating in a steady-state condition.
 3. Same as note (2), except the device is measured at t ≤ 10 sec.
 4. Same as note (2), except the device is pulsed with D= 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.
 5. Thermal resistance from junction to solder-point (at the end of the drain lead).



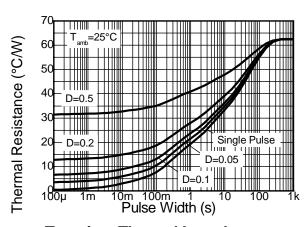
Thermal Characteristics

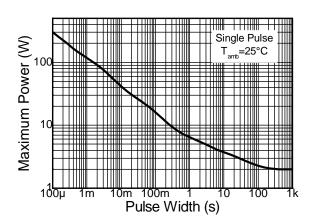




Safe Operating Area

Derating Curve





Transient Thermal Impedance

Pulse Power Dissipation





Electrical Characteristics @T_A = 25°C unless otherwise specified

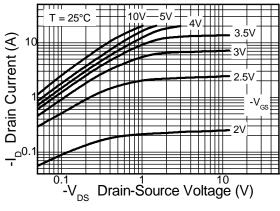
Characteristic	Symbol Min Typ Max Unit		Test Co	Test Condition				
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BV_{DSS}	-30	_	_	V	$I_D = -250 \mu A, V_{GS} = 0 V$		
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -30V, V_{GS} =$	= 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS}$	= 0V	
ON CHARACTERISTICS					•			
Gate Threshold Voltage	V _{GS(th)}	-1.0	_	_	V	$I_D = -250 \mu A, V_{DS}$	= V _{GS}	
Static Drain Source On Decistones (Note 6)	5			45	mΩ	$V_{GS} = -10V, I_D = -4.2A$		
Static Drain-Source On-Resistance (Note 6)	R _{DS (ON)}		_	70	11177	$V_{GS} = -4.5V, I_{D} =$	-3.4A	
Forward Transconductance (Notes 6 & 7)	9 _{fs}		9.2	_	S	$V_{DS} = -15V, I_{D} = -$	4.2A	
Diode Forward Voltage (Note 6)	V_{SD}		-0.85	-0.95	V	I _S = -3.6A, V _{GS} =	0V, T _J = 25°C	
Reverse recovery time (Note 7)	t _{rr}		21.7	_	ns	$I_F = -2A$, di/dt = 10	00A/μs,	
Reverse recovery charge (Note 7)	Q _{rr}	_	16.1	_	nC	$T_J = 25^{\circ}C$		
DYNAMIC CHARACTERISTICS (Note 7)					•			
Input Capacitance	C _{iss}		1022	_	pF	45)()(0) /	
Output Capacitance	Coss	_	267	_	pF	V _{DS} = -15V, V _{GS} = -f = 1MHz	= 0V	
Reverse Transfer Capacitance	Crss	_	229	_	pF			
Total Gate Charge (Note 8)	Qq	_	17.2	_	nC	$V_{GS} = -5V$		
Total Gate Charge (Note 8)	Qg	_	29.6	_	nC		V _{DS} = -15V	
Gate-Source Charge (Note 8)	Qgs	_	2.8	_	nC	$V_{GS} = -10V$	$I_D = -4.2A$	
Gate-Drain Charge (Note 8)	Q_{qd}	_	8.6	_	nC	1		
Turn-On Delay Time (Note 8)	t _{D(on)}	_	3.8	_	ns			
Turn-On Rise Time (Note 8)	t _r	_	6.5	_	ns	$V_{DD} = -15V, V_{GS} = -10V$		
Turn-Off Delay Time (Note 8)	t _{D(off)}	_	37.1	_	ns	$I_D = -1A$, $R_G \cong 6.0\Omega$		
Turn-Off Fall Time (Note 8)	t _f		21.4	_	ns	1		

Notes:

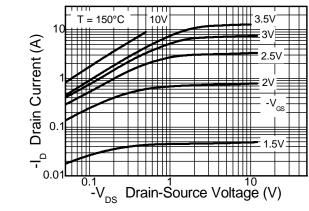
- 6. Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
 7. For design aid only, not subject to production testing.
 8. Switching characteristics are independent of operating junction temperatures.



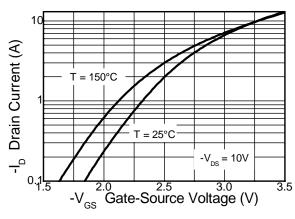
Typical Characteristics



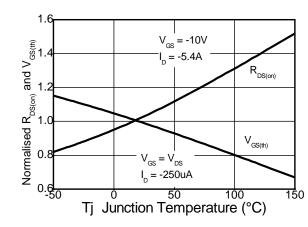
Output Characteristics



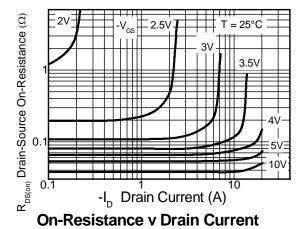
Output Characteristics



Typical Transfer Characteristics



Normalised Curves v Temperature



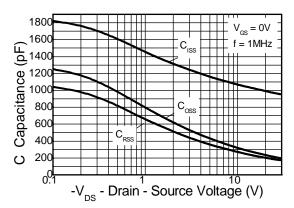
T = 150°C

T = 25°C

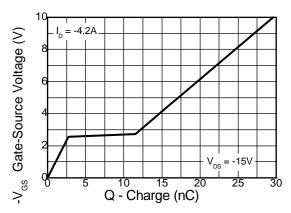
Source-Drain Diode Forward Voltage



Typical Characteristics – continued

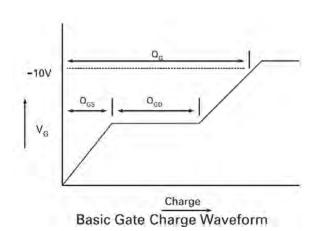


Capacitance v Drain-Source Voltage



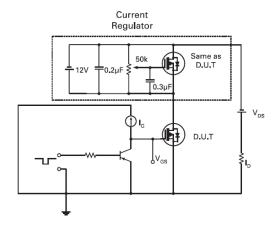
Gate-Source Voltage v Gate Charge

Test Circuits

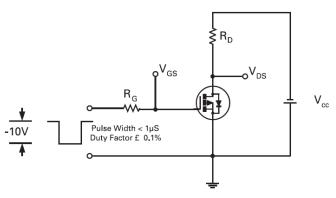


90% VDS

Switching Time Waveforms



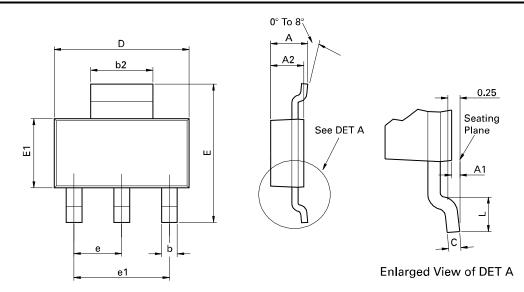
Gate Charge Test Circuit



Switching Time Test Circuit



Package Outline Dimensions

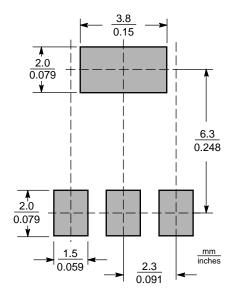


Conforms to JEDEC TO-261 AA Issue B

DIM	Millim	neters	Inc	hes	DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
Α	-	1.80	-	0.071	D	6.30	6.70	0.248	0.264
A1	0.02	0.10	0.0008	0.004	е	2.30 BSC		0.0905 BSC	
A2	1.55	1.65	0.0610	0.0649	e1	4.60 BSC		0.181 BSC	
b	0.66	0.84	0.026	0.033	Е	6.70	7.30	0.264	0.287
b2	2.90	3.10	0.114	0.122	E1	3.30	3.70	0.130	0.146
С	0.23	0.33	0.009	0.013	Ĺ	0.90	-	0.355	-

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches.

Suggested Pad Layout







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